



## Material Content Data Sheet



<b>Sales Product Name</b>				SAL-TC275TP-64F200N DC		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001661896					
<b>Package</b>				PG-LQFP-176-22		<b>Weight*</b>		1985.28 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	61.870	3.12	3.12	31164	31164	
leadframe	inorganic material	phosphorus	7723-14-0	0.136	0.01		68		
	non noble metal	zinc	7440-66-6	0.543	0.03		274		
	non noble metal	iron	7439-89-6	10.869	0.55		5475		
wire	non noble metal	copper	7440-50-8	441.312	22.23	22.82	222291	228108	
	noble metal	palladium	7440-05-3	0.034	0.00		17		
	non noble metal	copper	7440-50-8	3.351	0.17	0.17	1688	1705	
encapsulation	organic material	carbon black	1333-86-4	4.256	0.21		2144		
	plastics	epoxy resin	-	180.180	9.08		90758		
	inorganic material	silicondioxide	60676-86-0	1234.303	62.16	71.45	621727	714629	
leadfinish	noble metal	palladium	7440-05-3	0.004	0.00		2		
	noble metal	silver	7440-22-4	0.004	0.00		2		
	noble metal	gold	7440-57-5	0.007	0.00		4		
	non noble metal	nickel	7440-02-0	7.048	0.36	0.36	3550	3558	
plating	noble metal	silver	7440-22-4	0.016	0.00		8		
	noble metal	gold	7440-57-5	0.030	0.00		15		
	noble metal	palladium	7440-05-3	0.019	0.00		9		
	non noble metal	nickel	7440-02-0	30.469	1.53	1.53	15348	15380	
glue	plastics	epoxy resin	-	2.383	0.12		1200		
	noble metal	silver	7440-22-4	8.449	0.43	0.55	4256	5456	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com